# Design, Implementation and Analysis of Error Tolerant Adder in CMOS 180nm Technology

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Abstract— The main objective of this work is to design, implement and analyze the error tolerant adder (ETA) for DSP applications. This paper aims at designing ETA using low power and energy efficient one-bit full adders. Further we analyze ETA using state of the art one-bit full adders. All the ETA under consideration are designed by using CMOS 180nm technology. The design metrics such as power, delay, PDP and area in terms of transistor count are extracted under common Process-Voltage-Temperature (PVT) conditions. These design metrics are extracted for inputs signal frequency of 200MHz supply voltage of 1.8V and temperature of. All simulations are carried out using Cadence Spectre Simulator using BSIM Version 3 MOSFET models.

Index Terms—Adder, Delay, Power, PDP, ETA

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#### I. Introduction

The rapid advancements in VLSI technology due to continuous scaling will result in billions of devices and thousands of defects [1]. Further the advancement of VLSI process technology approaches the physical limits, process variations and quantum effects of nanometer circuits. Thus, manufacturing defect free chips is challenging. The traditional techniques to enhance the yield are fault and defect tolerance which have become inadequate. Thus, the importance of error-tolerance has received much attention in the current technology [2]. This results in low yield chips. A new way to enhance yield is error-tolerance [3]. A circuit is said to be error tolerant with respect to an application if it contains defects that cause internal and may cause external errors, and (2) the system that incorporates this circuit produces acceptable results.

The need for error-tolerance was foretold in the 2003 International Technology Roadmap for Semiconductors (ITRS) [4], where it was stated that "relaxing the requirement of 100% correctness in both transient and permanent failures of signals, logic values, devices, or interconnects may reduce the cost of manufacturing, verification and testing." How to cost-effectively identify acceptable defective chips is one of the central themes in this emerging field. Several attributes have been employed to evaluate the acceptability of defective chips and some corresponding measurement methods have also been developed in previous work. One of these attributes is error-rate [5].

Error tolerance (ET) scheme was proposed to increase effective yield. ET is a new design and test paradigm, which takes into consideration whether erroneous outputs of defective circuits produce acceptable results. ET classifies a chip as being acceptable/unacceptable by estimating the performance degradation due to faults, rather than relying solely on the conventional perfect/imperfect classification. ET analyzes the system-level effects of faults, and accepts chips if the performance degradation they lead to is within some, application-specific, ranges of acceptability [6].

Increasingly huge data sets and the need for instant response require the adder to be large and fast. The traditional ripple-carry adder (RCA) is therefore no longer suitable for large adders because of its low-speed performance. Many different types of fast adders, such as the carry-skip adder (CSK), carry-select adder (CSL), and carry-look-ahead adder (CLA) have been developed. Also, there are many low-power adder design techniques that have been proposed. However, there are always trade-offs between speed and power. The error-tolerant design can be a potential solution to this problem. By sacrificing some accuracy, the "error-tolerant-adder" (ETA) can attain great improvement in both the power consumption and speed performance [7].

## II. ADDITION ARITHMETIC IN ETA

In a conventional adder circuit, the delay is mainly attributed to the carry propagation chain along the critical path, from the Least Significant Bit (LSB) to the Most Significant Bit (MSB). Meanwhile, a significant proportion of the power consumption of an adder is due to the glitches that are caused by the carry propagation. Therefore, if the carry propagation can be eliminated or curtailed, a great improvement in speed performance and power consumption can be achieved.

# To minimize error due to the elimination of the carry chain

Check every bit position from left to right (MSB -LSB) starting from right of demarcation line. If both input bits are "0" or different, normal one-bit addition is performed and the operation, Proceeds to next bit position. The checking process is stopped when both input bits are encountered as high i.e., 1, and from this bit onwards, all sum bits to the right (LSB) are set to "1." This is how this adder Saves carry propagation delay and enhances the overall performance. An example for addition arithmetic is as shown in figure 1.

First split the input operands into two parts: an accurate part that includes several higher order bits and the inaccurate part that is made up of the remaining lower order bits. The length of each part need not necessary be equal. The addition process starts from the middle (joining point of the two parts) toward the two opposite directions simultaneously. In the example of

Figure 1, the two 16-bit input operands, A= "1011001110011010" (45978) and B= "011010010010011" (26899), are divided equally into 8 bits each for the accurate and inaccurate parts.

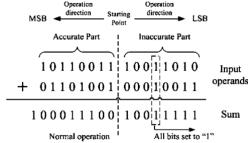


Fig 1: An example of addition arithmetic in ETA

The example given in Figure 1 should actually yield "100011100101101" (72877) if normal arithmetic has been applied. The overall error generated can be computed as OE = 72877-72863=14. By eliminating the carry propagation path in the inaccurate part and performing the addition in two separate parts simultaneously, the overall delay time is greatly reduced, so is the power consumption.

# III. DESIGN OF ERROR TOLERANT ADDER

Architecture of the error tolerant adder is shown in the figure 2. This is the most straight forward structure consists of two parts an accurate part and inaccurate part. The accurate part is constructed using the conventional adder such as the ripple carry adder. The carry-in of this accurate part is connected to ground. The inaccurate part constitutes of two blocks a carry free addition block and a control block. The control block is used to generate the control signals to determine the working mode of the carry-free addition block

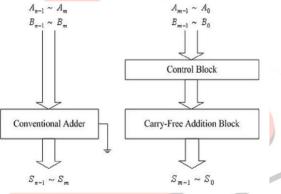


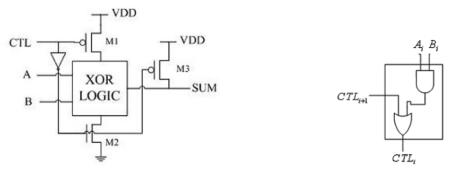
Fig 2: Architecture of ETA

#### IV. DESIGN OF ACCURATE PART

Ripple carry addition is the most power saving conventional addition technique. The ripple carry adder is built from cascading the full adders in series. It is used for addition logic in the accurate part. Hence each bit gets rippled in to the next stage. In a ripple carry adder the sum and carryout bits of any half adder stage is not valid until the carry in of the stage occurs. The propagation delay inside the logic circuitry is the reasons behind this, propagation delay is the time elapsed between the application of an input and occurrence of the corresponding output. Each block of the ripple carry adder is designed using conventional adder which is discussed in section 7.

# V. DESIGN OF INACCURATE PART

The inaccurate part is the most critical section in the ETA as it determines the accuracy, speed performance, and power consumption of the adder. The inaccurate part consists of two blocks: the carry-free addition block and the control block. The carry-free addition block is made up of modified XOR gates, and each of which is used to generate a sum bit. The carry-free addition block is designed using modified XOR gates to generate a sum bit individually for LSBs. The function of the control block is to detect the first bit position when both input bits are "1," and to set the control signal CTL to high at this position as well as those to its right up to LSB. The block diagram of the carry free addition block and the schematic implementation of the modified XOR gate is shown in figure 3 and its control logic block is shown in figure 4.



# Fig. 3: Modified XOR Gate

#### Fig. 4: Control Block

The modified XOR gates are then combined together to obtain the carry free addition block as shown the figure 5.

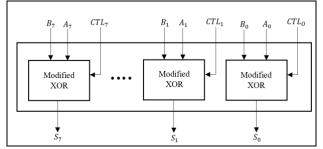


Fig 5: Architecture of Carry-Free Addition Block

## VI. SIMULATION ENVIRONMENT

The "design metrics" (DMs) such as delay, power, and PDP are extracted by applying standard test input patterns as shown in the figure 6 along with the transistor sizing of each buffer. To extract the DMs the input signals having frequency of 200 MHz and supply voltage of 1.8 V are applied through input buffers (to generate realistic input signals) for the "circuit under test" (CUT). The CUT outputs are connected to the load capacitance of 5.6 fF (to have realistic load conditions). Standard test input patterns is applied and delay and power is extracted and it is as shown in the figure 6 along with the transistor sizing of each buffer.

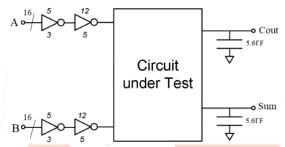


Fig 6: Simulation Testbench

## VII. RESULTS AND DISCUSSION

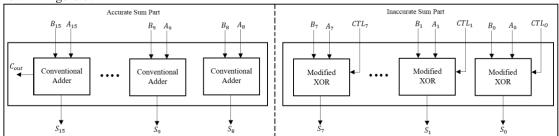
Based on the dividing strategy used depending on the size of Accurate Sum Part (ASP) and Inaccurate Sum Part (ISP) the following ETA's have been designed and analysed in terms of design metrics. In this paper Error tolerant adder is designed for four different combinations as shown in the table 1.

Table1: Design Metrics					
Adder	ASP	ISP			
ETA 1	8-Bit	8-Bit			
ETA 2	6-Bit	10-Bit			
ETA 3	4-Bit	12-Bit			
ETA 4	2-Bit	14-Bit			

Accurate Sum Part is designed using various one-bit full adders [8]-[10] in CMOS 180nm technology and the DMs power consumption, delay and area of the adder are tabulated in table below.

#### 1.ETA 1

In ETA1 the length of accurate part is 8 bit and length of inaccurate part is 8 bit. Accurate part is designed by connecting eight 1-bit full adders in series as shown in figure 7. Inaccurate part is designed using CMOS logic based XOR gate as shown in figure 7.



**Fig 7:** Architecture of ETA 1

Among all the adder 16T adder gives the less delay and low power and hence less PDP. It consumes 418 transistors. Simulation result is tabulated in table 2.

**Table 2:** Simulation Result for ETA 1

Tuble 2. Simulation Regalt for E1111					
ETA	Delay (n sec)	Power (m W)	PDP (pJ)	<b>Transistor Count</b>	
HPSC Adder	1.153	3.957	4.562	402	

New HPSC Adder	3.11	3.71	11.5381	434
Hybrid CMOS Adder	1.372	3.667	5.0311	418
TG CMOS Adder	2.29	3.386	7.7539	450
TFA Adder	2.773	3.28	9.0954	418
CMOS Adder	1.124	4.609	5.1805	450
DPL Adder	1.415	2.4	3.396	450
SRCPL Adder	1.506	2.412	3.6294	434
16T Adder	1.018	2.166	2.2049	418

## 2.ETA 2

In ETA 2 the length of accurate part is 6 bit and length of inaccurate part is 10 bit. Accurate part is designed by connecting six 1-bit full adders in series as shown in figure 8. Inaccurate part is designed using CMOS logic based XOR gate as shown in figure 8.

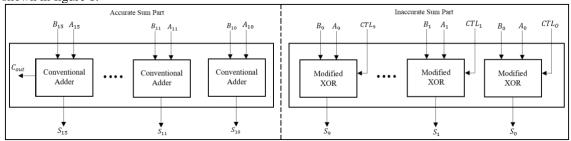


Fig 8: Architecture of ETA 2

Among all the adder 16T adder gives the less delay and low power and hence less PDP and area consumed is calculated in terms of transistor count, it consumes 428 transistors as shown in the table 3 below.

Table 2	: Simulation	Result	for	ETA	2
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ETA	Delay (n sec)	Power (m W)	PDP (pJ)	<b>Transistor Count</b>
HPSC Adder	0.8424	3.316	2.7933	416
New HPSC Adder	2.21	3.156	6.9747	440
Hybrid CMOS Adder	0.9789	3.15	3.0835	428
TG CMOS Adder	1.614	2.873	4.637	452
TFA Adder	1.887	2.818	5.3175	428
CMOS Adder	0.8301	3.663	3.0406	452
DPL Adder	1.024	2.239	2.2927	452
SRCPL Adder	1.086	2.247	2.24402	440
16T Adder	0.7614	2.052	1.5623	428

## **3.ETA 3**

In ETA 3 the length of accurate part is 4 bit and length of inaccurate part is 12 bit. Accurate part is designed by connecting four 1-bit full adders in series as shown in figure. Inaccurate part is designed using CMOS logic based XOR gate as shown in figure 9.

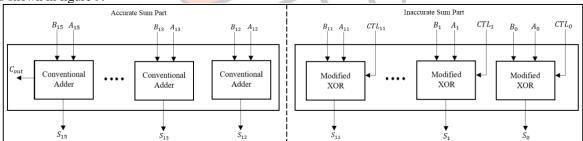


Fig 9: Architecture of ETA 3

Among all the adder 16T adder gives the less delay and low power and hence less PDP and area consumed is calculated in terms of transistor count, it consumes 438 transistors as shown in the table 4 below.

Table 4: Simulation Result for ETA 3

ETA	Delay (p sec)	Power (m W)	PDP (pJ)	<b>Transistor Count</b>
HPSC Adder	532	3.314	1.7630	430
New HPSC Adder	1310	3.161	4.1409	446
Hybrid CMOS Adder	585.4	3.191	1.8680	438
TG CMOS Adder	936.4	2.971	2.7820	454
TFA Adder	997.5	2.932	2.9246	438
CMOS Adder	535.7	3.489	1.8690	454
DPL Adder	633.4	2.523	1.5980	454
SRCPL Adder	664.9	2.534	1.6848	446
16T Adder	502.3	2.413	1.2120	438

#### 4.ETA 4

In ETA 4 the length of accurate part is 2 bit and length of inaccurate part is 14 bit. Accurate part is designed by connecting two 1-bit full adders in series as shown in figure. Inaccurate part is designed using CMOS logic based XOR gate as shown in figure 10.

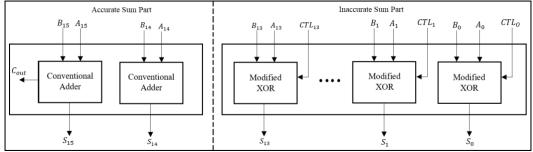


Fig 10: Architecture of ETA 4

Among all the adder 16T adder gives the less delay and low power and hence less PDP and area consumed is calculated in terms of transistor count, it consumes 448 transistors as shown in the table 5 below.

Table 4: Simulation Result for ETA 3					
ETA	Delay (p sec)	Power (m W)	PDP (pJ)	<b>Transistor Count</b>	
HPSC Adder	247.2	3.046	0.7529	444	
New HPSC Adder	419.1	2.988	1.2522	452	
Hybrid CMOS Adder	238.8	2.988	0.7135	448	
TG CMOS Adder	280.4	2.906	0.8148	456	
TFA Adder	268.4	2.903	0.7791	448	
CMOS Adder	241.8	3.106	0.7510	456	
DPL Adder	248.9	2.718	0.6765	456	
SRCPL Adder	249.9	2.722	0.6802	452	
16T Adder	240.2	2.67	0.6413	448	

**Table 4:** Simulation Result for ETA 3

# VIII. CONCLUSION

In this paper the simulation of ETA design is carried out using standard Cadence Virtuoso tools with 180 nm technology and compared its performance with other designs. The simulation results established that the 16T adder offered improved PDP compared with the earlier reports. The ETA design based on 16T adder is found to be low power and has an average power dissipation at input signal frequency of 200 MHz, supply voltage of 1.8 V, and load capacitance of 5.6 fF.

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